

Nanostructured Silicon for High Capacity Lithium Battery Anodes

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Electronic Supplementary Information (ESI): The following Data Tables summarize the morphology, composition, and method of preparation of those nanoscale and nanostructured silicon anodes reported in the recent literature, along with their electrochemical performance. When the appropriate electrochemical data was given in the report, we use the data directly. In all other cases, we have estimated the values from the information provided. For full details of the electrochemical performance, the reader is referred to the original report. In the tables, Q_{d1} corresponds to the first discharge (delithiation) capacity. The irreversible capacity in the first cycle (Q_{irr1}) is calculated as the difference between the first charge (lithiation) and discharge capacities. The reversible capacity ($Q_{r,N}$) is the discharge capacity in the N^{th} cycle.

Table ESI-1 Thin Films—Silicon

Morphology	Composition	Si (wt%)	Method	d Si (nm)	Potential (V)	Q_{d1} (mAh/g)	C_{irr1} (mAh/g)	$Q_{r,N}$ (mAh/g)	N Cycles	Reference
Thin film	Amorphous Si	100	Vacuum deposition onto pristine Ni foil	50	0.0 - 2.5	3750		3800	200	13
Thin film	Amorphous Si	100	Vacuum deposition onto pristine Ni foil	50	0.0 - 2.5	3350		3100	100	13
Thin film	Amorphous Si	100	Vacuum deposition onto pristine Ni foil	100	0.0 - 2.5			1850	5	13
Thin film	Amorphous Si	100	Vacuum deposition onto pristine Ni foil	150	0.0 - 2.5	2445		2300	200	13
Thin film	Amorphous Si	100	Vacuum deposition onto pristine Ni foil	150	0.0 - 2.5	2390	560	2390	5	13
Thin film	Amorphous Si	100	Sputtering onto pristine Cu foils	250	0.020 - 1.2	3500	600	3400	30	31
Thin film	Amorphous Si	100	Sputtering onto pristine Cu foils	1000	0.020 - 1.2	3080	300	2920	15	31
Thin film	Amorphous Si	100	Sputtering onto pristine Cu foils	250	0.020 - 1.2	3800	1280	3800	29	32
Thin film	Amorphous Si	100	Sputtering onto pristine Cu foils	1000	0.020 - 1.2	3050	340	3000	13	32
Thin film		100	Plasma enhanced chemical vapor deposition	300	0 - 2	3015		240	50	33
Thin film—coated		100	Plasma enhanced chemical vapor deposition, thermal evaporation	300		3260		3000	50	33
Thin film	Amorphous Si	100	Sputtering onto roughened Cu foil	3000	0.01 - 1	2200		1035	100	35
Thin Film	Amorphous Si	100	Resistive evaporation	100		2500	1021	1800	50	37
Thin Film	Nanocrystalline	100	Physical vapor transport/ballistic nanocrystal consolidation	100		1000	1400	525	50	37
Thin film		100	Vacuum deposition onto pristine Ni foil	100		2600	550	2100	400	38
Thin film		100	Vacuum deposition onto pristine Ni foil	200		3500	550	280	400	38
Thin film		100	Vacuum deposition onto mechanically roughened Ni foil	340		2300	470	1700	400	38
Thin film		100	Vacuum deposition onto mechanically roughened Ni foil	520		2440	560	1040	400	38
Thin film		100	Vacuum deposition onto chemically roughened Ni foil	1000		2650	< 100	1700	200	38
Thin film	Amorphous Si	100	Pulsed laser deposition onto pristine stainless steel	1500	0.005 - 1.5	52.6 μ Ah/cm ²	44.1 μ Ah/cm ²	40.0 μ Ah/cm ²	70	40
Thin film	Amorphous Si	100	Pulsed laser deposition onto pristine stainless steel	3000	0.005 - 1.5	51.1 μ Ah/cm ²	~ 10.5 μ Ah/cm ²	8.24 μ Ah/cm ²	70	40

Q_{d1} = 1st delithiation capacity; Q_{irr1} = irreversible capacity loss in the 1st cycle; $Q_{r,N}$ = reversible capacity in the Nth cycle; d Si = thickness of Si film.

Table ESI-1 (continued) Thin Films—Silicon

Morphology	Composition	Si (wt%)	Method	d Si (nm)	Potential (V)	Q_{d1} (mAh/g)	C_{irr1} (mAh/g)	$Q_{r,N}$ (mAh/g)	N Cycles	Reference
Thin film	Amorphous Si	100	Sputtering onto roughened Cu foil	200	0.02 - 1.2	3550	300	2450	50	41
Thin film	Amorphous Si	100	Sputtering onto roughened Cu foil	200	0.02 - 1.2	3060	650	540	50	41
Thin film	Amorphous Si	100	Sputtering onto roughened Cu foil	200	0.02 - 1.2	3250	330	3050	10	41
Thin film	Amorphous Si	100	Sputtering onto roughened Cu foil	800	0.02 - 1.2	1300	200	1350	10	41
Thin Film		100	E-beam evaporation	100	0.005 - 2	3560		3420	50	42
Thin Film		100	E-beam evaporation	100	0.005 - 2	3840		3420	80	42
Thin film		100	E-beam evaporation	200	0.005 - 2.0	3560	495	3500	45	43
Thin film		100	E-beam evaporation	200	0.005 - 2.0	3600	485	3000	100	43
Thin film	Amorphous Si	100	Sputtering onto pristine stainless steel	100		3400	950	2550	38	44
Thin film	Amorphous Si	100	Sputtering onto roughened Ni foil	100		2942	690	2665	60	45
Thin film	Amorphous Si	100	Sputtering onto roughened Cu foils		0.01 - 2.0	946	1480	125	30	46
Thin film	Amorphous Si	100	Sputtering onto roughened Cu foils with Ni buffer layer		0.01 - 2.0	1622	1904	265	30	46
Thin film	Amorphous Si	100	Chemical vapor deposition	425 - 540	0.0 - 1.5	3768		3025	40	47
Thin film	Amorphous Si	100	Sputtering onto pristine Ni foil	100	0.1 - 1.5	2530	770	2510	10	48
Thin film	Amorphous Si	100	Sputtering onto pristine Ni foil	100	0.1 - 1.5	1881	566	210	10	48
Thin film	Amorphous Si	100	Resistive evaporation onto roughened Cu foil	6000	0.01 - 2.0	1230	1670	960	20	49
Thin film	Nanocrystalline	100	Pulsed laser deposition onto pristine stainless steel	42	0.1 - 1.5	3500	600	2200	200	50
Thin film	Nanocrystalline	100	Pulsed laser deposition onto pristine stainless steel	42	0.1 - 1.5	4000	1750	190	200	50
Thin film	Amorphous Si	100	Sputtering onto roughened Cu foil	275	0 - 1.5	2148		1317	500	51

Q_{d1} = 1st delithiation capacity; Q_{irr1} = irreversible capacity loss in the 1st cycle; $Q_{r,N}$ = reversible capacity in the Nth cycle; d Si = thickness of Si film.

Table ESI-2. Thin Films—Composite

Morphology	Composition	Si (wt%)	Method	d Si (nm)	Potential (V)	Q_{d1} (mAh/g)	C_{irr1} (mAh/g)	$Q_{r,N}$ (mAh/g)	N Cycles	Reference
Thin film	Amorphous alloy with nanocrystalline phases	86	Sputtering onto roughened Cu foil	3100	0.01 - 1	2000		1210	100	35
Thin film	Amorphous alloy with nanocrystalline phases	60	Sputtering onto roughened Cu foil	3450	0.01 - 1	1800		1240	100	35
Thin film	Amorphous alloy with nanocrystalline phases	27	Sputtering onto roughened Cu foil	4770	0.01 - 1	1500		1180	100	35
Thin film—multilayered	Fe/Si layers		E-beam evaporation	630	0 - 1.2	386 μ Ah/cm ²		376 μ Ah/cm ²	46	39
Thin film—multilayered	Fe/Si layers		E-beam evaporation, annealing	630	0 - 1.2	490 μ Ah/cm ²		436 μ Ah/cm ²	50	39
Thin film—codeposition	Nanocrystalline Cu embedded in amorphous Si		Sputtering onto pristine Cu foil		0.0 - 2.0	405 μ Ah/cm ² μ m ⁻¹	335 μ Ah/cm ² μ m ⁻¹	350 μ Ah/cm ² μ m ⁻¹	40	53

Q_{d1} = 1st delithiation capacity; Q_{irr1} = irreversible capacity loss in the 1st cycle; $Q_{r,N}$ = reversible capacity in the Nth cycle; d Si = thickness of composite film.

Table ESI-3 Nanowires and Nanotubes—Silicon

Morphology	Composition	Si (wt%)	Method	d Si (nm)	Potential (V)	Q_{d1} (mAh/g)	C_{irr1} (mAh/g)	$Q_{r,N}$ (mAh/g)	N Cycles	Reference
Pillars	Silicon	100	Reactive ion etching of Si substrates	580	0.025 - 2	54 μ Ah/cm ²	52 μ Ah/cm ²	41 μ Ah/cm ²	50	54
Nanowire	Silicon	100	Chemical vapor deposition	89	0.01 - 2.0	3124	1153	3120	10	55
Nanowire	Silicon	100	Chemical vapor deposition	89	0.01 - 2.0	3600		3400	20	55
Nanowire	Crystalline core/Amorphous shell	100	Chemical vapor deposition		0.01 - 2.0	2500	610	1975	30	56
Nanowire	Crystalline core/Amorphous shell	100	Chemical vapor deposition		0.15 - 2.0	1060	200	900	100	56
Nanotube	Polycrystalline Si	100	Chemical vapor deposition	120	0.01 - 2.0	3360	500	2670	50	57
Nanotube	Polycrystalline Si	100	Chemical vapor deposition	120	0.01 - 2.0	2645	279	2160	50	57
Nanowire	Silicon	100	Metal catalytic etching of Si	20 - 300	0.02 - 2	2267	1390	1130	10	59
Nanowire	Silicon	100	Chemical vapor deposition	100	0.01 - 2.0	3706	119	1600	50	66

Q_{d1} = 1st delithiation capacity; Q_{irr1} = irreversible capacity loss in the 1st cycle; $Q_{r,N}$ = reversible capacity in the Nth cycle; d Si = diameter of nanowire or nanotube.

Table ESI-4 Nanowires and Nanotubes—Composite

Morphology	Composition	Si (wt%)	Method	d Si (nm)	Potential (V)	Q_{d1} (mAh/g)	C_{irr1} (mAh/g)	$Q_{r,N}$ (mAh/g)	N Cycles	Reference
Nanowire	Butyl-capped Si gel		Chemical reduction		0 - 1.5	3163	501	2738	80	58
Nanowire	Silicon nanowires/ Carbon coating		Metal catalytic etching of Si, pyrolysis	20 - 300	0.02 - 2	2810	534	1326	40	59
Nanofiber	Silane - Carbon nanofibers	88	Chemical vapor deposition		0.01 - 1	2015	222	1710	50	60
Nanotubes	Butyl-capped Si gel - SnO_2 nanotubes	40	Chemical reduction	10	0 - 1.2	1838	990	1600	90	61
Nanowire	Butyl-capped Si gel		Chemical reduction	200 - 250		3247	401			62
Nanowire	Silicon - sucrose – carbon black	82	Supercritical fluid-liquid-solid growth, pyrolysis	25	0.01 - 1	2453	2997	410	75	63
Nanowire	Silicon - sucrose - multi- walled carbon nanotubes	98.5	Supercritical fluid-liquid-solid growth, pyrolysis	25	0.01 - 1	1500	2750	1050	75	63
Nanowire	Silicon - graphite	15	Electroless Etching	100 - 200	0.01 - 1.5	600	211	512	64	50
Nanotube	Silicon - carbon nanotubes		Chemical vapor deposition	40	0.02 - 1.2	2049	503	2050	25	67

Q_{d1} = 1st delithiation capacity; Q_{irr1} = irreversible capacity loss in the 1st cycle; $Q_{r,N}$ = reversible capacity in the Nth cycle; d Si = diameter of nanowire or nanotube.

Table ESI-5 Nanoparticles—Silicon

Morphology	Composition	Si (wt%)	Method	d Si (nm)	Potential (V)	Q_{d1} (mAh/g)	C_{irr1} (mAh/g)	$Q_{r,N}$ (mAh/g)	N Cycles	Reference
Microcrystalline Si	Si	100	Milling	3000 - 5000	0.05 - 1.2	900	100	800	10	78
Microcrystalline Si	Si	100	Milling	3000	0 - 1.2	500		200	5	90
Microcrystalline Si	Si	100	Milling	< 2000	0 - 1.2	765		595	55	90
Nanoparticles	Si	100	Commercial powder	100			350	1200	700	91
Nanocrystalline Si	Si	100	Solvothermal	5	0 - 1.5	2649	1794	1880	40	114
Nanocrystalline Si	Si	100	Solvothermal	10	0 - 1.5	3380	830	2738	40	114
Nanocrystalline Si	Si	100	Solvothermal	20	0 - 1.5	3467	613	2323	40	114

Q_{d1} = 1st delithiation capacity; Q_{irr1} = irreversible capacity loss in the 1st cycle; $Q_{r,N}$ = reversible capacity in the Nth cycle; d Si = diameter of nanoparticle.

Table ESI-6 Other Morphologies—Silicon

Morphology	Composition	Si (wt%)	Method	d Si (nm)	Potential (V)	Q_{d1} (mAh/g)	C_{irr1} (mAh/g)	$Q_{r,N}$ (mAh/g)	N Cycles	Reference
Nest-like	Si	100	Solvothermal		0.02 - 1.6	3952				106
Nest-like	Si	100	Solvothermal		0.02 - 1.6	3052		1095	48	106
Coil-like	Si	100	Solvothermal		0.02 - 1.6	3550				106

Q_{d1} = 1st delithiation capacity; Q_{irr1} = irreversible capacity loss in the 1st cycle; $Q_{r,N}$ = reversible capacity in the Nth cycle; d Si = diameter of nanoparticle.

Table ESI-7 Nanoparticles—Composite

Morphology	Composition	Si (wt%)	Method	d Si (nm)	Potential (V)	Q_{d1} (mAh/g)	C_{irr1} (mAh/g)	$Q_{r,N}$ (mAh/g)	N Cycles	Reference
Nanocrystalline Si/ Graphite	Si - graphite	10 atom %	Milling	~ 40		700		380	20	68
Nanocrystalline Si/ Graphite	Si - graphite	20 atom %	Milling	~ 10		1040		800	20	68
Nanocrystalline Si/ Ni/Ni ₂ Si/graphite	Si - graphite - nickel stearate	20	Milling, thermal decomposition		0.001 - 1.5	680	260	495	30	79
Silicon/Cellulose/ Carbon Black	Si - cellulose - carbon black (SE2)	50	Mixing, heat treatment		0 - 1.5	2560 (2 nd cycle)		1800	50	85
Silicon/Cellulose/ Carbon Black	Si - cellulose - carbon black (Super P)	50	Mixing, heat treatment		0 - 1.5	2820 (2 nd cycle)		1300	50	85
Nanocrystalline Si/ Nanocrystalline Ag	Si - AgNO ₃	80	Milling, electroless deposition	< 100	0.02 - 1.5	2347	382	1150	15	86
Nanocrystalline Si/ Nanocrystalline Ag	Si - AgNO ₃	64.1	Milling, electroless deposition		0.01 - 1.2	700	250	620	30	87
Si Nanoparticles/ Amorphous C	Si - carbon black		Laser ablation, manual grinding	~ 78	0 - 0.8	2780		1300	22	89
Si nanoparticles/ Graphite	SiH ₄ - graphite	20	Pyrolysis	~ 50	0.005 - 1.0	1350	350	900	115	92

Q_{d1} = 1st delithiation capacity; Q_{irr1} = irreversible capacity loss in the 1st cycle; $Q_{r,N}$ = reversible capacity in the Nth cycle; d Si = diameter of Si in nanoparticle.

Table ESI-7 (continued) Nanoparticles—Composite

Morphology	Composition	Si (wt%)	Method	d Si (nm)	Potential (V)	Q_{d1} (mAh/g)	C_{irr1} (mAh/g)	$Q_{r,N}$ (mAh/g)	N Cycles	Reference
Nanocrystalline Si/NiSi	Si - Ni	49	Milling	40	0.001 - 1.2	1135	115	530	50	93
Si Nanoparticles/TiC	Si - Li-Ti-O sol	65	Sol-gel synthesis with Si nanoparticles	30 - 50	0.02 - 3	1250	790	1240	80	94
Silicon-Tin alloy/Carbon	Si - Sn - C	89	Chemical reduction	10	0 - 1.2	2032	500	1971	60	96
Microcrystalline Si/ Microcrystalline SnSb	Si - SnSb		Carbothermal reduction	5 - 10 μm	0.01 - 1.5	970	205	905	10	104
Si particles/CNTs	Si - CNTs		Electroless deposition, chemical vapor deposition		0.0 - 2.0	1675		1245	12	105
Silicon/Graphite/Single-walled Nanotubes	Si - SWNTs - graphite	35	Milling, heat treatment		0.02 - 1.2	960	922	865	30	107
Silicon/Graphite/SWNTs	Si - SWNTs - graphite	45	Milling, heat treatment		0.02 - 1.2	1121	751	922	30	107
Silicon/Graphite/SWNTs	Si - SWNTs - graphite	45	Milling, functionalization, heat treatment		0.02 - 1.2	1130	655	1066	30	107
Silicon/Graphite	Si - graphite	15.5	Chemical grafting of silicon to graphite	50	0.01 - 1	1503	644	540	50	112
Silicon/Graphite	Si - graphite	9	Chemical modification, mixing	50	0.01 - 1	1049	494	303	50	112

Q_{d1} = 1st delithiation capacity; Q_{irr1} = irreversible capacity loss in the 1st cycle; $Q_{r,N}$ = reversible capacity in the Nth cycle; d Si = diameter of Si in nanoparticle.

Table ESI-7 (continued) Nanoparticles—Composite

Morphology	Composition	Si (wt%)	Method	d Si (nm)	Potential (V)	Q_{d1} (mAh/g)	C_{irr1} (mAh/g)	$Q_{r,N}$ (mAh/g)	N Cycles	Reference
Nanocrystalline Si/Disordered C	Si - sucrose	71	Milling, pyrolysis	59	0.02 - 1.2	842	420	587	20	69
Nanocrystalline Si/Disordered C	Si - sucrose	76	Milling, pyrolysis		0.02 - 1.2	815		485	20	69
Nanocrystalline Si/Disordered C	Si - sucrose	90	Milling, pyrolysis		0.02 - 1.2	738		195	20	69
Nanocrystalline Si/Disordered C	Si - polyvinyl alcohol	71	Milling, pyrolysis	17	0.02 - 1.2	935	230	755	20	69
Nanocrystalline Si/Disordered C	Si - polyvinyl alcohol	80	Milling, pyrolysis		0.02 - 1.2	904		650	20	69
Nanocrystalline Si/Disordered C	Si - polyvinyl alcohol	93	Milling, pyrolysis		0.02 - 1.2	738		267	20	69
Si nanoparticles/Amorphous C	Si - polypyrrole	50	Milling	300 - 3000	0.02 - 1.2	1100		765	10	70
Si nanoparticles/Amorphous C	Si - polypyrrole	90	Milling	300 - 3000	0.02 - 1.2	1800		600	10	70
Nanocrystalline Si/Amorphous C	Si - citric acid	44	Spray pyrolysis	< 100 nm	0.02 - 1.20	1857	743	1489	20	71
Nanocrystalline Si/Amorphous SiO _x -Amorphous C	SiO - furfuryl alcohol - graphite		Milling, pyrolysis	5 to 10	0.01 - 1.5	700		640	200	72
Nanocrystalline Si/Amorphous C	Si - graphite - resin	24	Milling	25	0.02 - 1.2	599	281	640	30	73
Nanocrystalline Si/Amorphous C	Si - poly(vinyl) chloride	44	Pyrolysis	7	0 - 2	985	170	840	20	74
Nanocrystalline Si/Amorphous C	Si - poly(vinyl) chloride	44	Pyrolysis	> 100	0 - 2	1200	175	600	20	74
Nanocrystalline Si/Graphite/LiCl	SiCl ₄ - LiC ₆	9.3	Chemical reduction	42	0.005 - 3	608	125	525	10	75
Nanocrystalline Si/LiCl	SiCl ₄ - Li	9.1	Milling	10 to 30	0.005 - 3	533	185	370	10	75
Si nanoparticles/Amorphous C	Si - PVdF		Pyrolysis	~ 60	0.02 - 1.5	1495		970	16	76
Si nanoparticles/Amorphous C	Si - PVC		Pyrolysis	~ 60	0.02 - 1.5	1825		1150	16	76
Si nanoparticles/Amorphous C	Si - CPE		Pyrolysis	~ 60	0.02 - 1.5	1930		1215	16	76
Nanocrystalline Si/Amorphous C	Si - PVdF		Milling, pyrolysis	60	0.02 - 1.5	745		600	50	76

Q_{d1} = 1st delithiation capacity; Q_{irr1} = irreversible capacity loss in the 1st cycle; $Q_{r,N}$ = reversible capacity in the Nth cycle; d Si = diameter of Si in nanoparticle.

Table ESI-7 (continued) Nanoparticles—Composite

Morphology	Composition	Si (wt%)	Method	d Si (nm)	Potential (V)	Q _{d1} (mAh/g)	C _{irr1} (mAh/g)	Q _{r,N} (mAh/g)	N Cycles	Reference
Si nanoparticles/Graphite	Si - graphite	33	Milling	100-2000	0.001 - 1.5	1091	402	770	50	77
Si nanoparticles/Graphite/Polymer	Si - graphite - polymer microspheres (5%)	33	Milling	100-2000	0.001 - 1.5	1060	369	830	50	77
Si nanoparticles/Graphite/Polymer	Si - graphite - polymer microspheres (10%)	33	Milling	100-2000	0.001 - 1.5	1065	318	885	50	77
Crystalline Si/Amorphous C	Si - benzene	73	Milling, pyrolysis	3000 - 5000	0.05 - 1.2	950	50	750	70	78
Si nanoparticles/Amorphous C	Partially oxidized Si - pitch	10	Milling, pyrolysis	22	0.01 - 2	465	115	360	10	80
Si nanoparticles/Amorphous C	Si - pitch	10	Milling, pyrolysis	22	0.01 - 2	460	105	335	15	80
Si nanoparticles/Amorphous C	Si - pitch	15	Milling, pyrolysis	22	0.01 - 2	576	120	400	15	80
Crystalline Si/Amorphous C	Si - citric acid		Milling, pyrolysis, annealing	1000 - 2000	0.02 - 1.50	1570		627	30	81
Nanocrystalline Si/Amorphous C	Si - glucose	74	Milling, hydrothermal coating	50 - 80	0 - 1.5	824	1001	800	30	82
Nanocrystalline Si/Amorphous C	Si - graphite - polypropylene	< 10	Mixing	60	0.005 - 1	750	165	325	14	83
Nanocrystalline Si/Amorphous C	Si - graphite	10	Mixing, pyrolysis	60	0.005 - 1	750	102	575	14	83
Nanocrystalline Si/Cu/Amorphous C	Si - resorcinol-formaldehyde	31.5	Milling, pyrolysis		0.0 - 2.0	910	290	683	20	84
Nanocrystalline Si/Amorphous C	Si - Cu - resorcinol-formaldehyde		Milling, pyrolysis		0.0 - 2.0	518	152	487	20	84
Nanocrystalline Si/Amorphous C	Si - benzene	73	Milling, pyrolysis	~ 3000	0 - 1.2	980		1000	55	90
Nanocrystalline Si/Amorphous C	Si - citric acid	73	Spray pyrolysis	< 100	0.02 - 1.2	1830	1220	275	100	95
Nanocrystalline Si/Amorphous C	Si - citric acid	44	Spray pyrolysis	< 100	0.02 - 1.2	1857	743	1120	100	95
Nanocrystalline Si/Amorphous C	Si - citric acid	15	Spray pyrolysis	< 100	0.02 - 1.2	427	663	125	100	95
Nanocrystalline Si/Amorphous C	Butyl-capped Si	90	Chemical reduction	5	0 - 1.5	1257	365	1055	30	96
Nanocrystalline Si/Amorphous SiO _x -Amorphous C	Si - SiO _x - resorcinol-formaldehyde	23	Pyrolysis	30 - 50	0 - 2	930	800	330	20	97

Q_{d1} = 1st delithiation capacity; Q_{irr1} = irreversible capacity loss in the 1st cycle; Q_{r,N} = reversible capacity in the Nth cycle; d Si = diameter of Si in nanoparticle.

Table ESI-7 (continued) Nanoparticles—Composite

Morphology	Composition	Si (wt%)	Method	d Si (nm)	Potential (V)	Q_{d1} (mAh/g)	C_{irr1} (mAh/g)	$Q_{r,N}$ (mAh/g)	N Cycles	Reference
Nanocrystalline Si/Amorphous SiO_x	Si - SiO_x	88	Pyrolysis	30 - 50	0 - 2	1480		330	20	97
Nanocrystalline Si//graphite/amorphous C	Si-graphite-phenyl-formaldehyde resin		Pyrolysis, milling		0.01 - 1.5	700	275	550	40	98
Nanocrystalline Si//graphite/amorphous C	Si-phenyl-formaldehyde resin		Pyrolysis, milling		0.01 - 1.5	875	325	310	40	98
Nano Si/Amorphous C	Si - polypyrrole	46.6	Mixing, pyrolysis	40	0.02 - 1.2	841		250	100	99
Nanocrystalline Si/Carbon black/Amorphous carbon	Si - carbon black - propylene	~ 50	Chemical vapor deposition, pyrolysis	10 - 30	0 - 1.1	1590		1530	100	100
Amorphous Si and pregraphitic C	Si - $(\text{CH}_3)_2\text{Cl}_2\text{Si}$	5.9 atom %	Chemical vapor deposition/pyrolysis			600	120	478	34	101
Amorphous Si and pregraphitic C	Si - $(\text{CH}_3)_2\text{Cl}_2\text{Si}$	11 atom %	Chemical vapor deposition/pyrolysis			640	160	493	34	101
Si/Amorphous C	Si - poly(vinyl) chloride	19.4	Pyrolysis	< 100	0.02 - 1.5	605	170	500	30	102
Si/Amorphous C	Si - poly(vinyl) chloride - graphite	19.6	Pyrolysis	< 100	0.02 - 1.5	730	150	670	30	102
Si/Amorphous C	Si - petroleum pitch - graphite	20.8	Pyrolysis	< 100	0.02 - 1.5	640		325	27	102
Nanocrystalline Si/Amorphous C	Si - phenol formaldehyde - graphite	13	Pyrolysis	< 100	0.02 - 1.5	500	200	440	40	103
Nanocrystalline Si/Amorphous C	Si - phenol formaldehyde - graphite		Pyrolysis	< 100	0.02 - 1.5	550		515	40	103
Nanocrystalline Si/Amorphous C	Butyl-capped Si gel	88	Hard templating, pyrolysis	40 - 100	0 - 1.2	2820	318	2780	100	110
Nanocrystalline Si/Amorphous C	Butyl-capped Si gel	88	Hard templating, pyrolysis	40 - 100	0 - 1.2	2670		2440	100	110
Carbon inverse-opals/Amorphous silicon	Sucrose - Disilane		Hard templating, chemical vapor deposition		0.05 - 2	2406	973	2132	145	111
Nanocrystalline Si/Amorphous C	Si – PVdF	95.7	Pyrolysis/ hand milling	< 100	0.02 - 1.5	1329	1057	1290	30	113
Nanocrystalline Si/Amorphous C	Si - acetylene	94	Pyrolysis	10	0 - 1.5	3535	437	3394	40	114

Q_{d1} = 1st delithiation capacity; Q_{irr1} = irreversible capacity loss in the 1st cycle; $Q_{r,N}$ = reversible capacity in the Nth cycle; d Si = diameter of nanowire or nanotube.